

ATTORNEY DOCKET NO: 70408RCE4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : SCHREDL et al.  
Serial No : 10/020,594  
Confirm. No. : 7149  
Filed : December 13, 2001  
For : CONTACT STRUCTURE FOR...  
Art Unit : 1793  
Examiner : Kevin P. Kerns  
Dated : January 28, 2009

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

The following references have been cited in a Japanese Office Action dated July 9, 2008 and/or cited in a Japanese Office Action dated December 24, 2008.

- JP 09-148693 discloses a flip chip mounting board and manufacture thereof. The reference has been cited in both Office Actions. No translation is available at this time, however, attached is an English language abstract.

- JP 04-037147 discloses a mounting of semiconductor chip. The reference has been cited in both Office Actions. No translation is available at this time, however, attached is an English language abstract.

- JP 09-134934 discloses a semiconductor package and semiconductor device. The reference has been cited in both Office Actions. No translation is available at this time, however, attached is an English language abstract.

- JP 10-153270 discloses a wiring board with joining bump. The reference has been cited in the Office Action dated December 24, 2008. No translation is available at this time, however, attached is an English language abstract.

Consideration of the above references is requested.

Respectfully submitted  
for Applicant,



By: \_\_\_\_\_  
John James McGlew  
Registration No. 31,903  
McGLEW AND TUTTLE, P.C.

JJM:tf  
70408RCE4-8

Enclosed: PTO/SB/08a Form  
copy of (4) References and (4) English Abstracts

DATED: January 28, 2009  
SCARBOROUGH STATION  
SCARBOROUGH, NEW YORK 10510-0827  
(914) 941-5600

SHOULD ANY OTHER FEE BE REQUIRED, THE PATENT AND TRADEMARK OFFICE IS HEREBY REQUESTED TO CHARGE SUCH FEE TO OUR DEPOSIT ACCOUNT 13-0410.